

L Number	Hits	Search Text	DB	Time stamp
1	55	((324/754-762.ccls. and pressure)and polish\$)and wafer	USPAT; US-PGPUB	2002/06/12 17:30
2	0	((324/754-762.ccls. and pressure)and polish\$)and wafer) and polish near plate	USPAT; US-PGPUB	2002/06/12 16:41
3	1	("5657394").PN.	USPAT; US-PGPUB	2002/06/12 16:41
4	1301	324/754-762.ccls. and pressure	USPAT; US-PGPUB	2002/06/12 17:30
5	133	324/754-762.ccls. and polish\$	USPAT; US-PGPUB	2002/06/12 17:30

L Number	Hits	Search Text	DB	Time stamp
10	1483	324/754-762.ccls. and pressure	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/06/12 12:23
11	230	(324/754-762.ccls. and pressure) and chuck\$	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/06/12 12:25
12	208	((324/754-762.ccls. and pressure) and chuck\$) and wafer	USPAT; EPO; JPO; DERWENT; IBM_TDB	2002/06/12 12:25